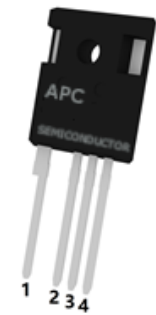
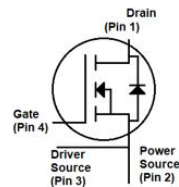




# High Power SiC MOSFET Transistor

## AMR075V120H1



### Applications:

- Solar Inverters
- Uninterrupted power supplies
- Switch mode power supplies
- Motor drives

### Features:

- High blocking voltage with low on-resistance
- High switching speed with low capacitance
- Very low switching losses
- Excellent avalanche ruggedness
- Very fast and robust intrinsic body diode with low reverse recovery

### Absolute Maximum Ratings (T<sub>amb</sub>=25°C, unless specified otherwise)

Symbol	Parameter	AMR075V120H1	Unit
V <sub>DS</sub>	DC Reverse Voltage	1200	V
V <sub>GSmax</sub>	Gate-source voltage, max. transient voltage	-10/+22	
V <sub>GSmax</sub>	Gate-source voltage, max. static voltage	-8/+19	
V <sub>GSop</sub>	Gate-source voltage	-4/ +15	
I <sub>D</sub>	Continuous drain current (V <sub>GS</sub> = 15V), T <sub>C</sub> = 25°C	35	A
	Continuous drain current (V <sub>GS</sub> = 15V), T <sub>C</sub> = 100°C	25	
I <sub>D(pulse)</sub>	Pulsed drain current	88	A
P <sub>tot</sub>	Power dissipation	170	W
T <sub>j</sub>	Operating junction temperature	-55 to 175	°C
T <sub>stg</sub>	Storage temperature	-55 to 175	°C
M	Mounting torque	1	Nm

### Thermal and Mechanical Characteristics

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
R <sub>θJC</sub>	Junction-to-case thermal Resistance		-	0.60	-	°C/W
R <sub>θJA</sub>	Junction-to-ambient thermal Resistance		-	-	40	°C/W

**Static Electrical Characteristics (T<sub>A</sub> = 25 °C, unless specified otherwise)**

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>BV<sub>DSS</sub></b>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 100 uA	1200	-	-	V
<b>V<sub>GS(th)</sub></b>	Gate-Source Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 5mA	2	3	4	
		V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 5mA, T <sub>J</sub> = 175°C	-	2	-	
<b>I<sub>DSS</sub></b>	Drain-Source Leakage current	V <sub>DS</sub> = 1200V, V <sub>GS</sub> = 0V	-	1	50	uA
<b>I<sub>GSS</sub></b>	Gate-Source leakage current	V <sub>GS</sub> = 15V, V <sub>DS</sub> = 0V	-	1	250	nA
<b>R<sub>DS(on)</sub></b>	Drain-Source ON Resistance	V <sub>GS</sub> = 15 V, I <sub>D</sub> = 20A	-	72	92	mΩ
		V <sub>GS</sub> = 15 V, I <sub>D</sub> = 20A, T <sub>J</sub> = 175°C	-	115	-	
<b>g<sub>fs</sub></b>	Transconductance	V <sub>DS</sub> =20V I <sub>D</sub> = 20A	-	18	-	S
		V <sub>DS</sub> =20V I <sub>D</sub> = 20A, T <sub>J</sub> = 175°C	-	14	-	
<b>R<sub>g(int)</sub></b>	Internal gate resistance	f=1MHz, V <sub>AC</sub> =25mV	-	1.4	-	Ω

**Dynamic Characteristics (T<sub>A</sub> = 25 °C, unless specified otherwise)**

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
<b>C<sub>iss</sub></b>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 1000V, f = 1MHz, V <sub>AC</sub> = 25mV	-	882	-	pF
<b>C<sub>rss</sub></b>	Reverse Transfer Capacitance		-	2	-	
<b>C<sub>oss</sub></b>	Output Capacitance		-	42	-	
<b>E<sub>oss</sub></b>	C <sub>oss</sub> stored energy		-	24	-	μJ
<b>Q<sub>gs</sub></b>	Gate-Source Gate Charge	V <sub>DD</sub> = 800V,	-	19	-	nC
<b>Q<sub>gd</sub></b>	Gate-Drain Gate Charge	V <sub>GS</sub> = -4/+15V,	-	23	-	
<b>Q<sub>g</sub></b>	Total Gate Charge	I <sub>D</sub> = 20A, I <sub>GS</sub> = 1mA	-	61	-	

**Switching Characteristics (T<sub>A</sub> = 25 °C, unless specified otherwise)**

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$T_{d(on)}$	Turn-on delay time	$V_{DD} = 800V,$ $V_{GS} = -4/+15V, I_D = 20A,$ $R_{G(ext)} = 5.1\Omega, L = 110\mu H,$ $T_j = 25^\circ C$	-	12	-	ns
$T_r$	Rise time		-	20	-	
$T_{d(off)}$	Turn-off delay time		-	23	-	
$T_f$	Fall time		-	13	-	
$E_{on}$	Turn On Switching Energy		-	321	-	$\mu J$
$E_{off}$	Turn Off Switching Energy	-	16	-		
$T_{d(on)}$	Turn-on delay time	$V_{DD} = 800V,$ $V_{GS} = -4/+15V, I_D = 20A,$ $R_{G(ext)} = 5.1\Omega, L = 110\mu H,$ $T_j = 175^\circ C$	-	10	-	ns
$T_r$	Rise time		-	20	-	
$T_{d(off)}$	Turn-off delay time		-	27	-	
$T_f$	Fall time		-	14	-	
$E_{on}$	Turn On Switching Energy		-	439	-	$\mu J$
$E_{off}$	Turn Off Switching Energy		-	18	-	

**Body Diode Characteristics ( $T_A = 25^\circ C$ , unless specified otherwise)**

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
$V_{SD}$	Body Diode Forward Voltage	$V_{GS} = -4V, I_{SD} = 10A$		3.5		V
		$V_{GS} = -4V, I_{SD} = 10A,$ $T_j = 175^\circ C$		3.1		
$I_S$	Continuous diode forward current	$T_C = 25^\circ C$	-	-	35	A
$t_{rr}$	Reverse recovery time	$V_{GS} = -4V, I_{SD} = 20A,$ $V_R = 800V,$	-	12	-	ns
$Q_{rr}$	Reverse recovery charge		-	0.22	-	$\mu C$
$I_{rrm}$	Peak reverse recovery current	$di/dt = 3.84kA/\mu s,$ $T_j = 25^\circ C$	-	30	-	A
$t_{rr}$	Reverse recovery time	$V_{GS} = -4V, I_{SD} = 20A,$ $V_R = 800V,$	-	22	-	ns
$Q_{rr}$	Reverse recovery charge		-	0.52	-	$\mu C$
$I_{rrm}$	Peak reverse recovery current	$di/dt = 3.89kA/\mu s,$ $T_j = 175^\circ C$	-	37	-	A

**Electrical Characteristic Diagrams**

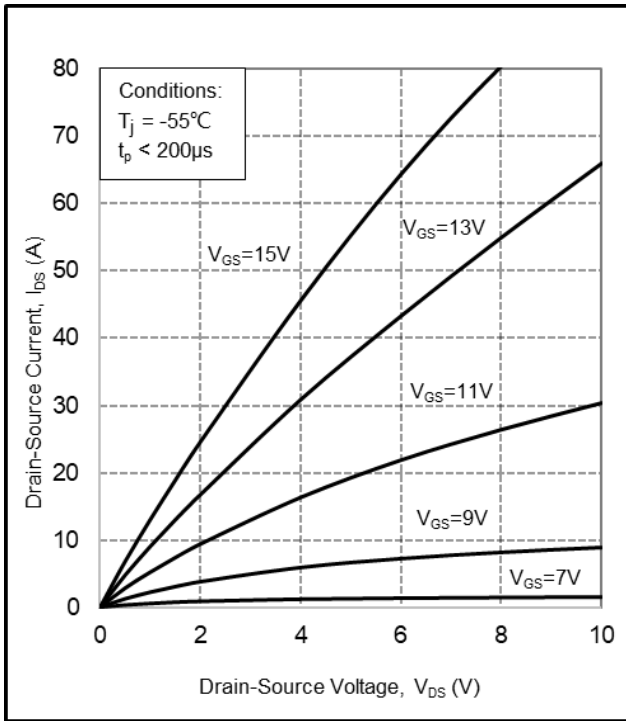


Figure 1. Output characteristics at  $T_j = -55^\circ\text{C}$

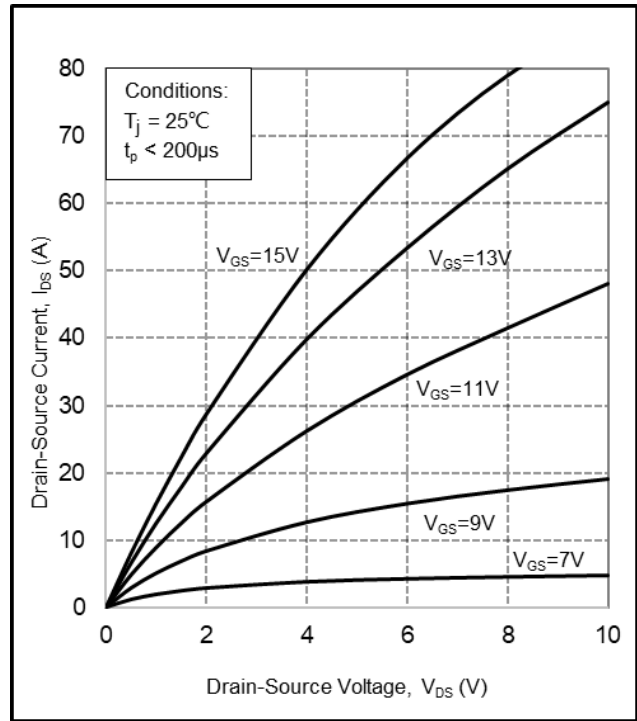


Figure 2. Output characteristics at  $T_j = 25^\circ\text{C}$

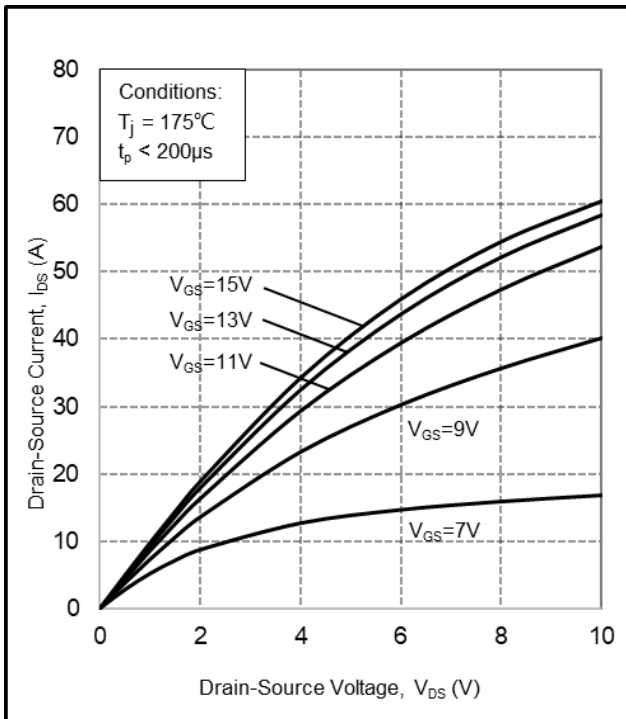


Figure 3. Output characteristics at  $T_j = 175^\circ\text{C}$

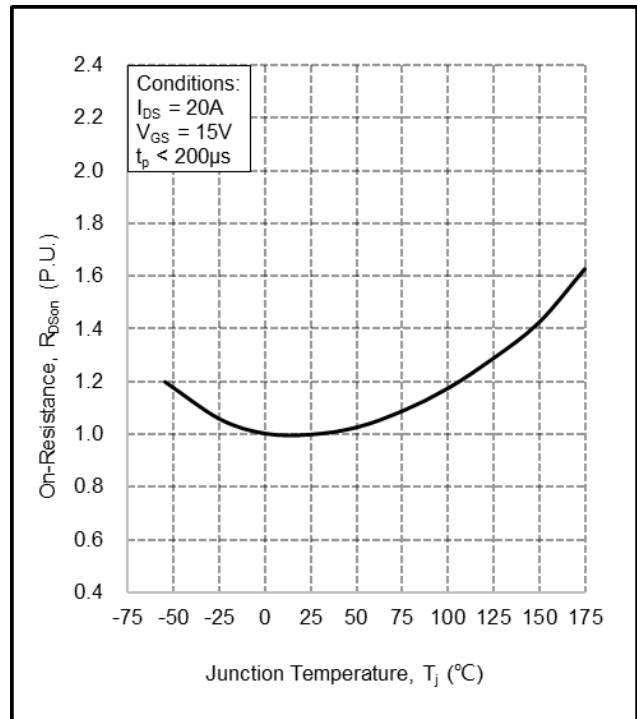


Figure 4. Normalized on-resistance vs. temperature

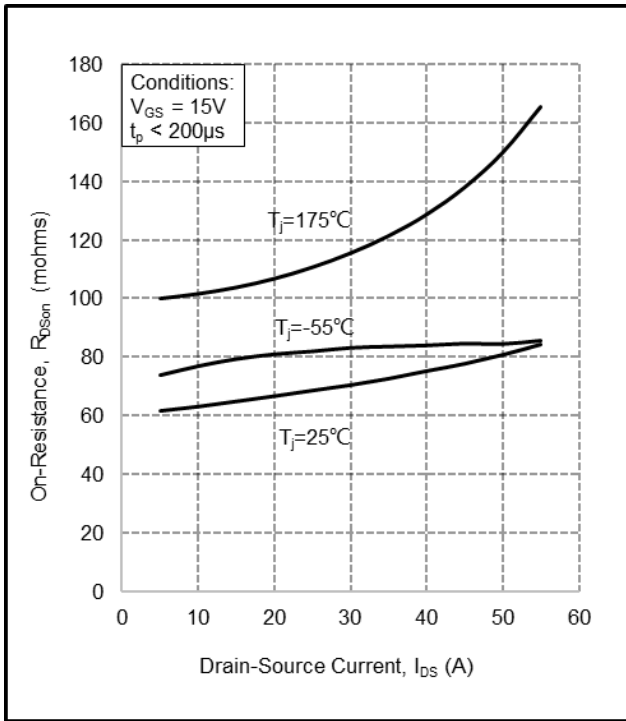


Figure 5. On-resistance vs. drain current for various temperatures

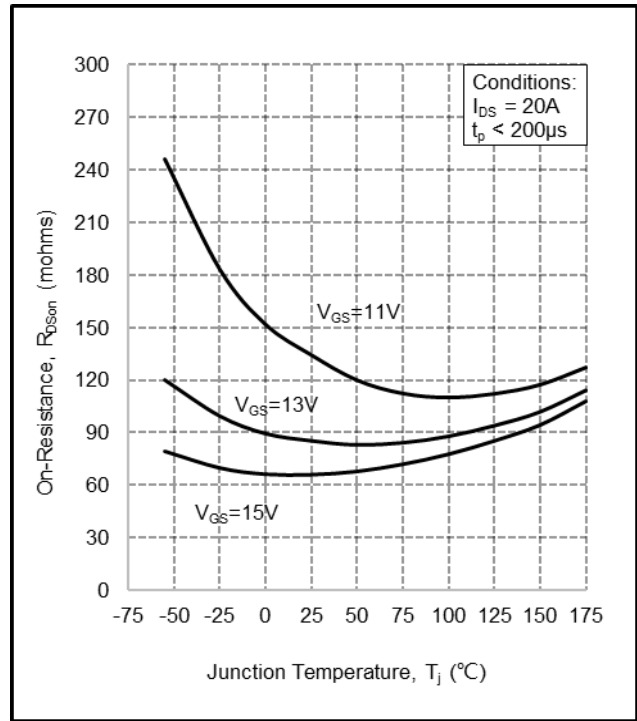


Figure 6. On-resistance vs. temperature for various gate voltages

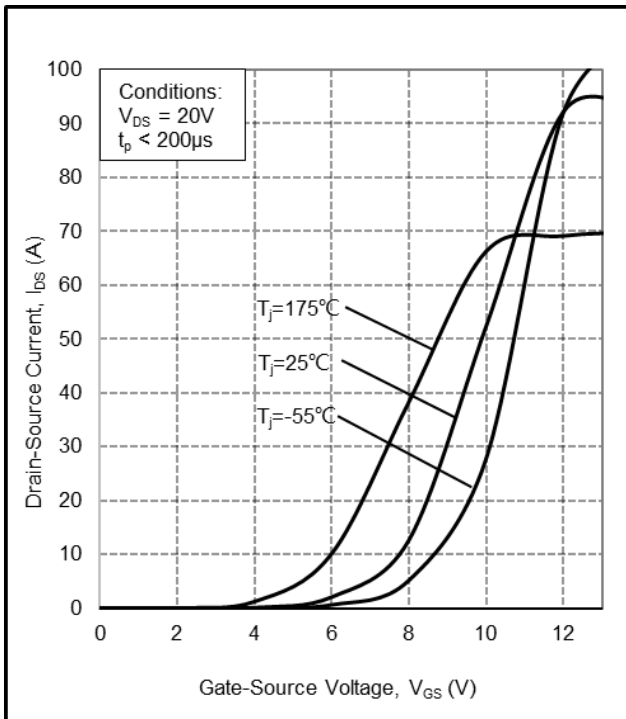


Figure 7. Transfer characteristic for various junction temperatures

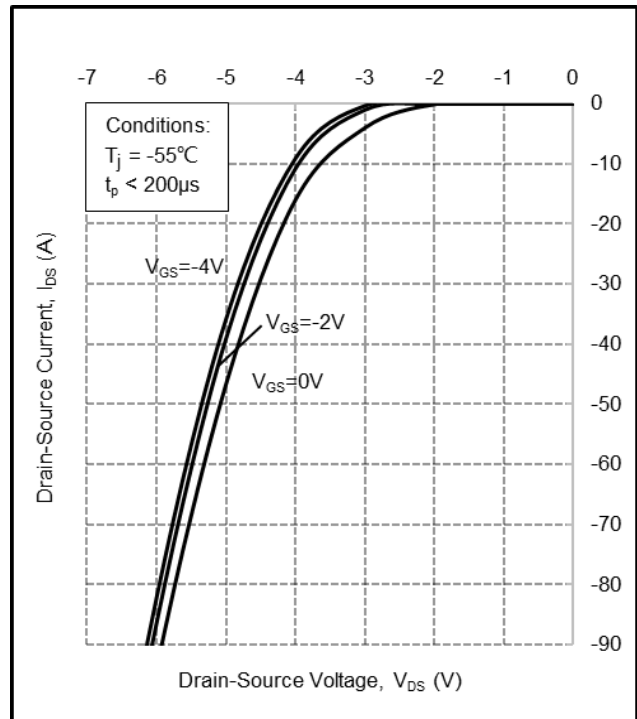


Figure 8. Body diode characteristic at  $T_J = -55^\circ\text{C}$

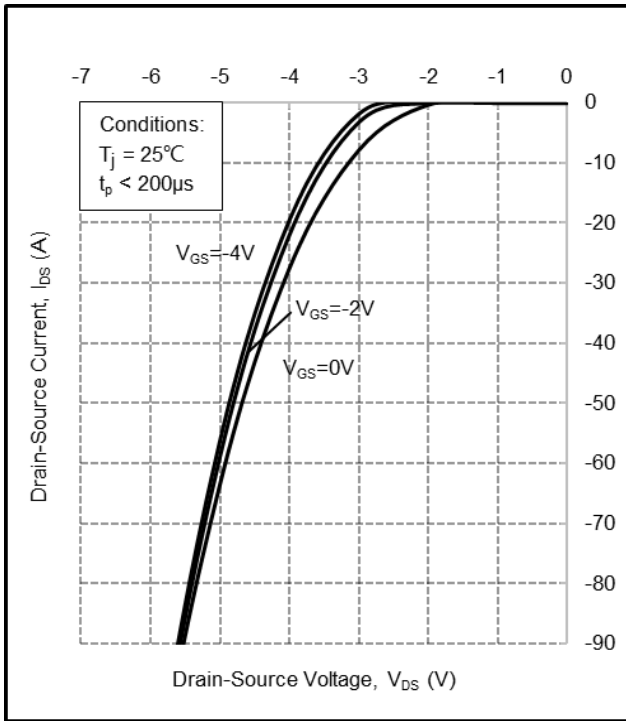


Figure 9. Body diode characteristic at  $T_j = 25^\circ\text{C}$

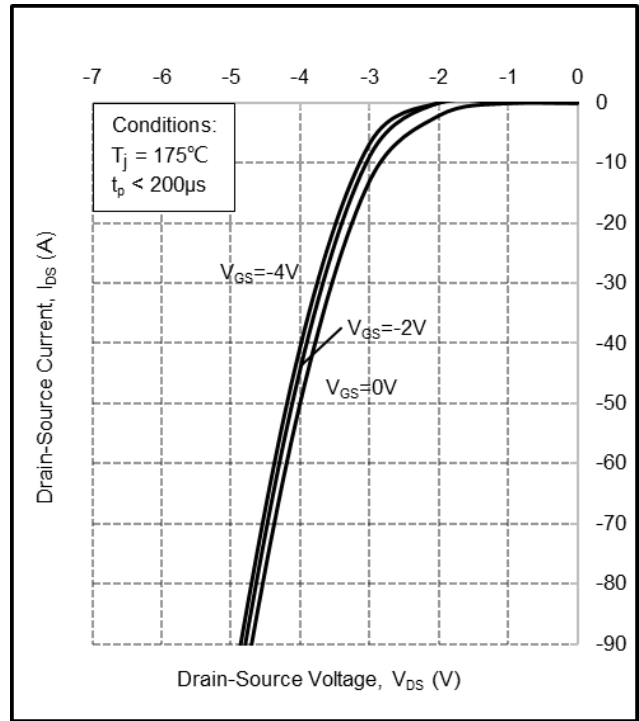


Figure 10. Body diode characteristic at  $T_j = 175^\circ\text{C}$

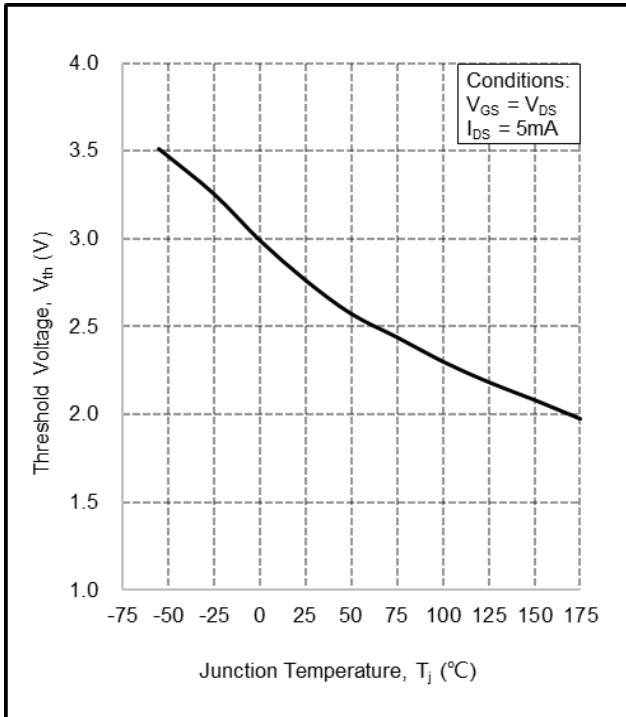


Figure 11. Threshold voltage vs. temperature

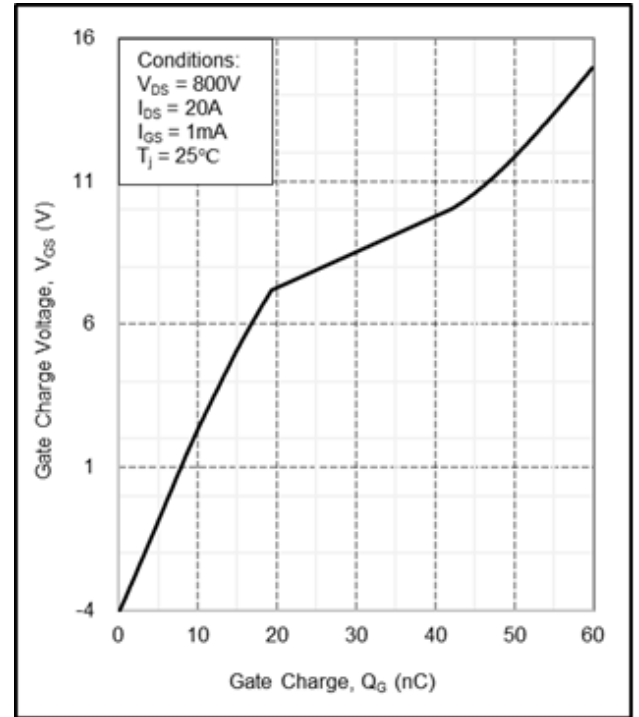


Figure 12. Gate charge characteristics

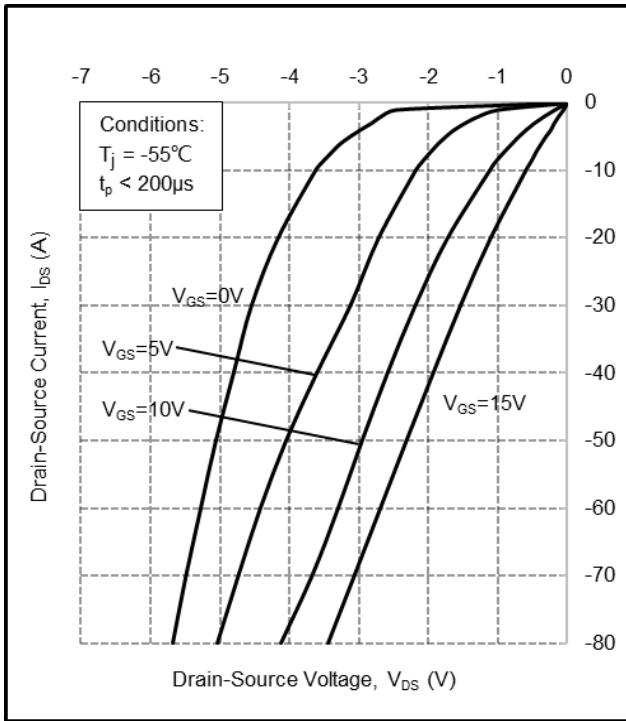


Figure 13. 3rd quadrant characteristic  
at  $T_j = -55^\circ\text{C}$

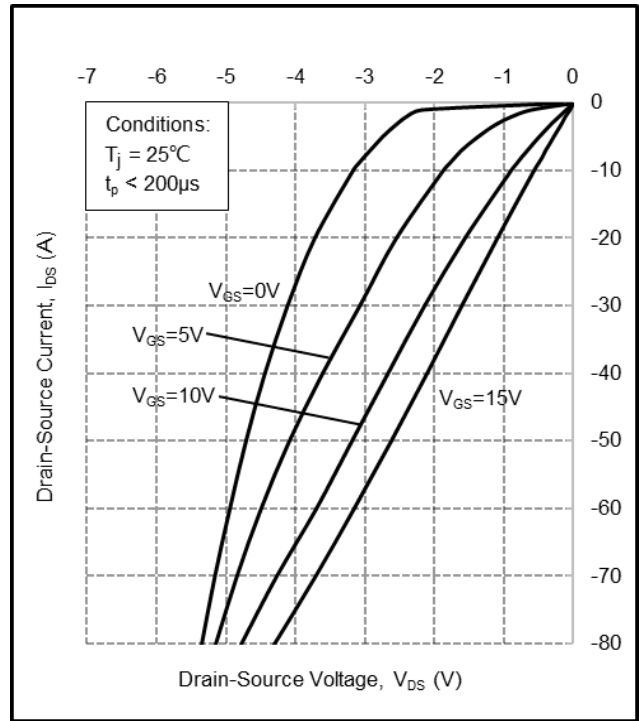


Figure 14. 3rd quadrant characteristic  
at  $T_j = 25^\circ\text{C}$

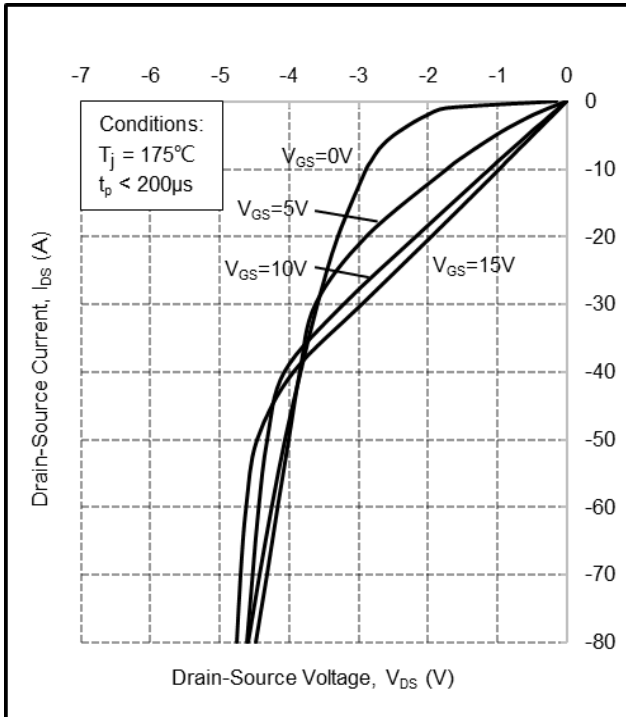


Figure 15. 3rd quadrant characteristic  
at  $T_j = 175^\circ\text{C}$

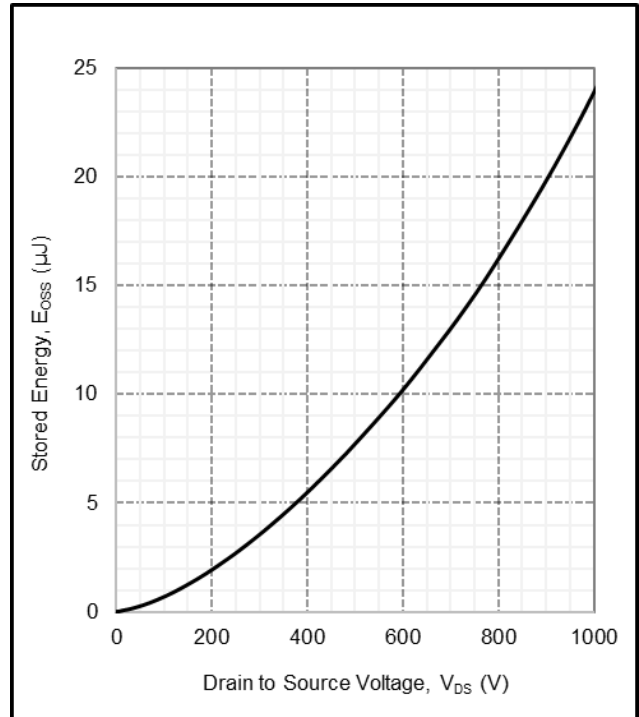


Figure 16. Output capacitor stored energy

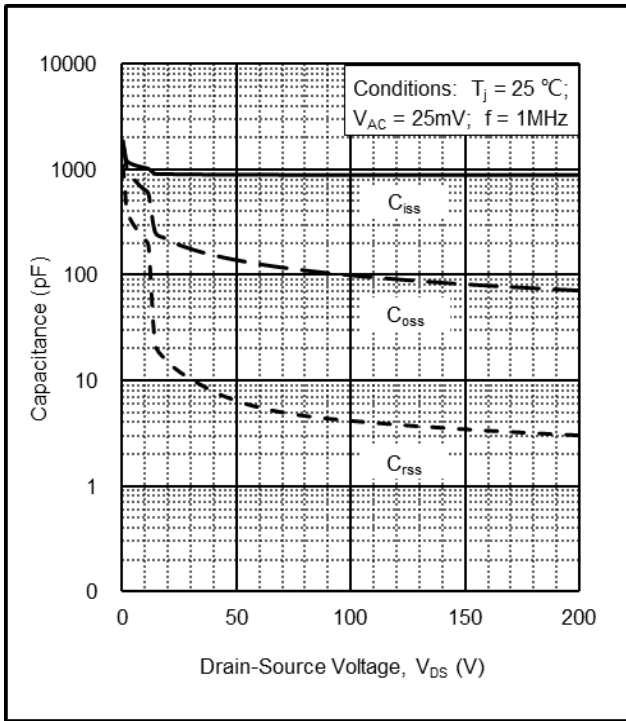


Figure 17. Capacitance vs. drain-source voltage (0 - 200V)

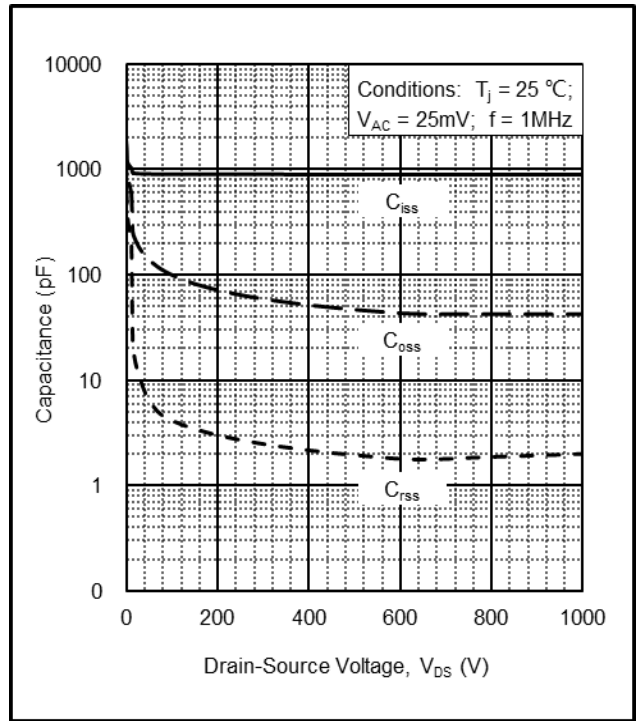


Figure 18. Capacitance vs. drain-source voltage (0 - 1000V)

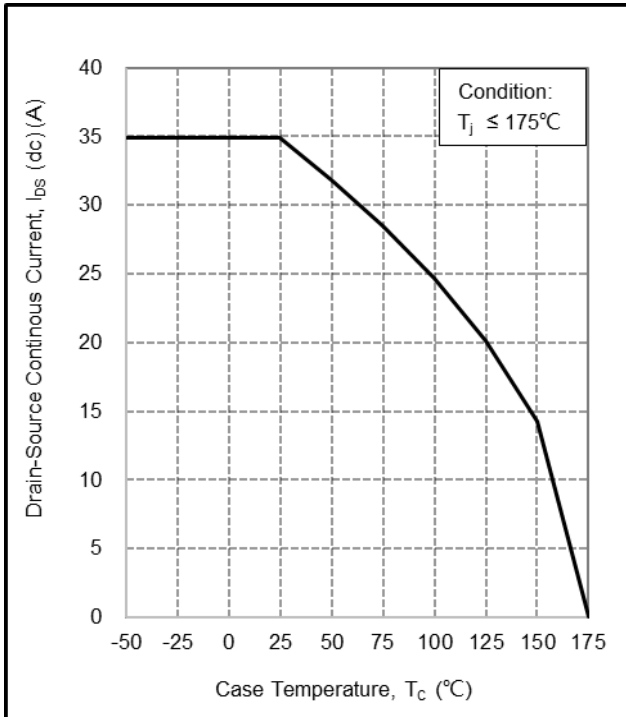


Figure 19. Continuous drain current derating vs. temperature

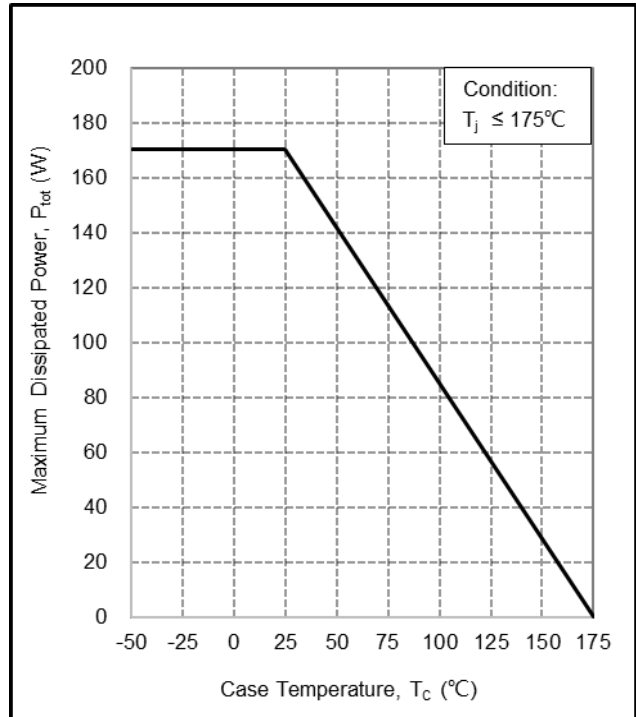


Figure 20. Maximum power dissipation derating vs. temperature



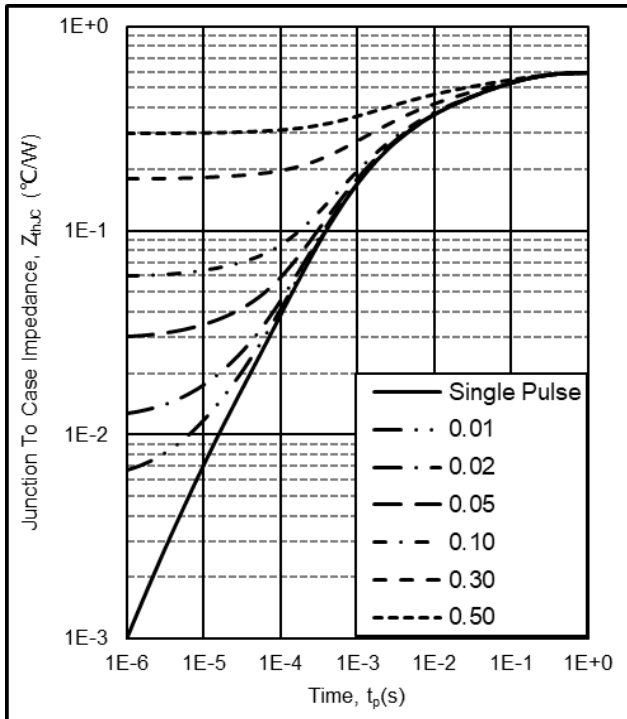


Figure 21. Transient thermal impedance  
(Junction - Case)

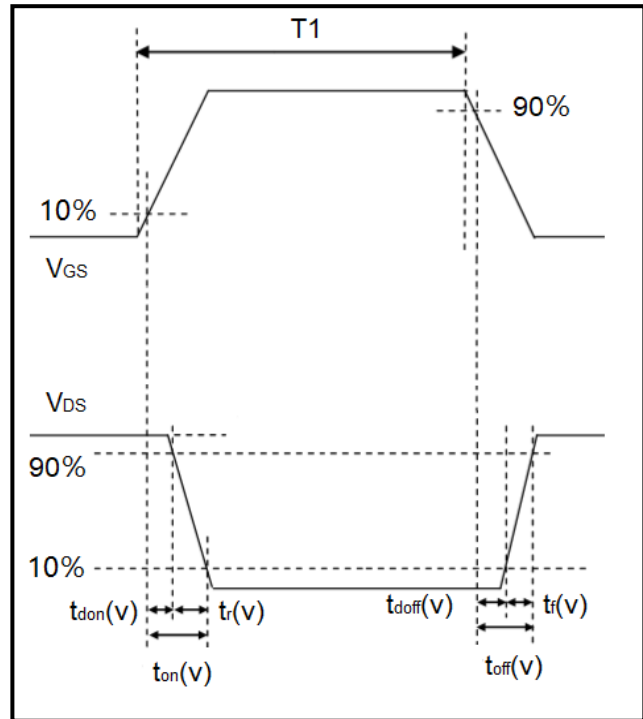


Figure 22. Switching times definition

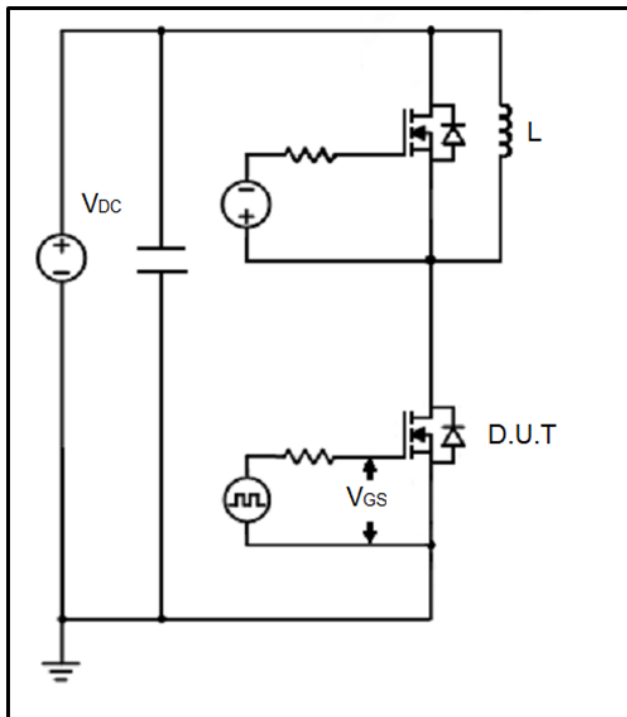
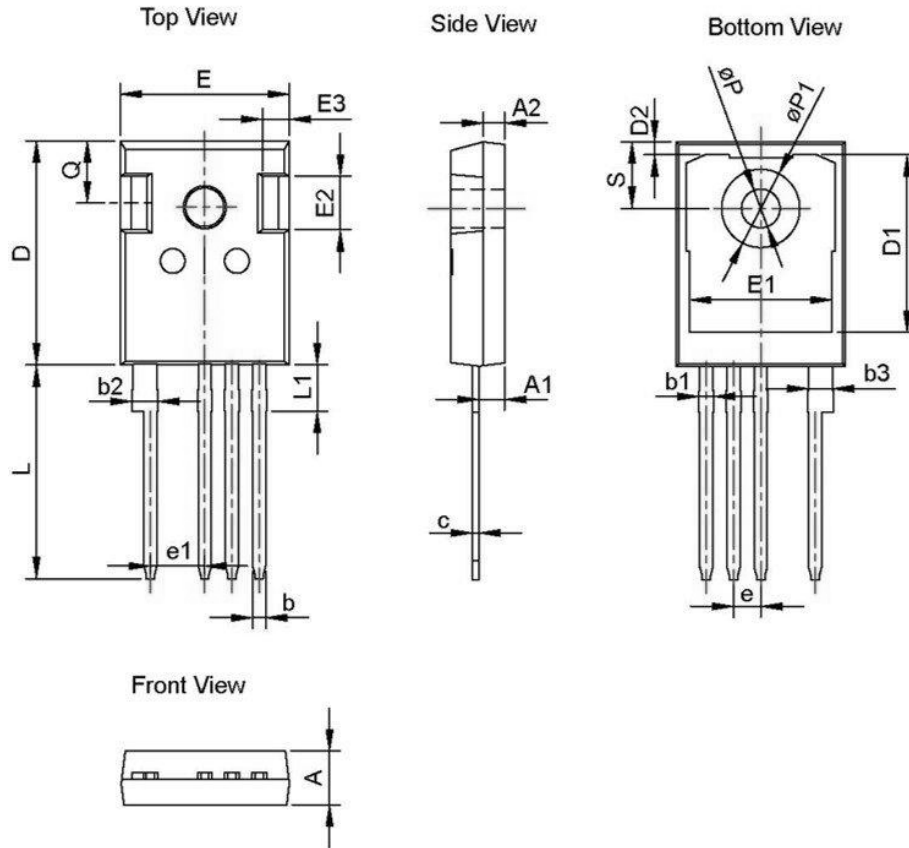


Figure 23. Clamped inductive switching waveform  
test circuit

**Package Information:**

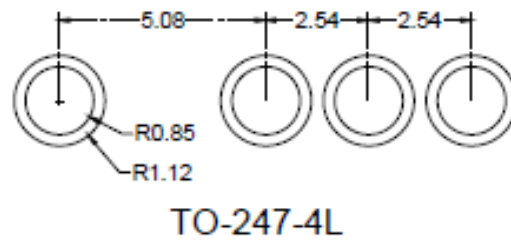


Dimension unit: [mm]			
Symbol	Min	Nom	Max
A	4.80	5.00	5.20
A1	2.21	2.41	2.61
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b1	1.11	1.37	1.57
b2	2.24	2.40	2.60
b3	2.11	2.21	2.36
c	0.51	0.60	0.75
D	20.70	20.90	21.30
D1	15.92	16.22	16.52
D2	1.00	1.20	1.35
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	2.54 BSC		
e1	5.08 BSC		

Dimension unit: [mm]			
Symbol	Min	Nom	Max
L	19.62	19.92	20.22
L1	-	-	4.30
$\phi P$	3.40	3.60	3.80
$\phi P1$	-	-	7.30
Q	5.40	5.80	6.20
S	6.20 BSC		

## Recommended Solder Pad Layout

Note: All dimensions are in mm



## Ordering Information

Part number	AMR075V120H1
Package	TO-247-4L
Unit quantity	300 EA
Packing type	Tube

For more information, visit <https://www.apowerc2.com>